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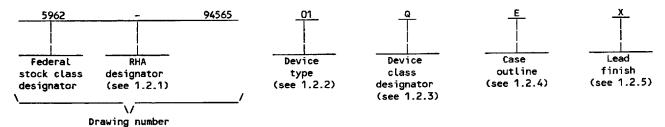
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### 1, SCOPE

- 1.1 <u>Scope</u>. This drawing forms a part of a one part one part number documentation system (see 6.6 herein). Two product assurance classes consisting of military high reliability (device classes Q and M) and space application (device class V), and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). Device class M microcircuits represent non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices". When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.
  - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>RHA designator</u>. Device class M RHA marked devices shall meet the MIL-I-38535 appendix A specified RHA levels and shall be marked with the appropriate RHA designator. Device classes Q and V RHA marked devices shall meet the MIL-I-38535 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
  - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01 02 03 04	MAX220 MAX222 MAX232A MAX242	Dual RS-232 driver/receiver, low power Dual RS-232 driver/receiver, shutdown Dual RS-232 driver/receiver, high speed Dual RS-232 driver/receiver, shutdown and enable
<b>0</b> 5	MAX243	Dual RS-232 driver/receiver, open-line detection

1.2.3 <u>Device class designator</u>. The device class designator shall be a single letter identifying the product assurance level as follows:

Device class

# Device requirements documentation

M

Vendor self-certification to the requirements for non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883

Q or V

Certification and qualification to MIL-I-38535

1.2.4 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	<u>Package style</u>
E	GDIP1-T16 or CDIP2-T16	16	Dual-in-line
V	GDIP1-T18 or CDIP2-T18	18	Dual-in-line
2	CQCC1-N2O	20	Square leadless chip carrier

1.2.5 <u>Lead finish</u>. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein) for class M or MIL-I-38535 for classes Q and V. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

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1.3 Absolute maximum ratings. -0.3 V dc to  $V_{CC}$  - 0.3 V dc -25 V dc to +25 V dc -15 V dc to +15 V dc -0.3 V dc to  $V_{CC}$  + 0.3 V dc Short circuit duration, driver and receiver outputs . . Continuous Power dissipation (P<sub>D</sub>),  $T_A = +70^{\circ}C$ : 1/2/800 mW 842 mW 727 mW Thermal resistance, junction-to-case  $(\theta_{JC})$  . . . . . Thermal resistance, junction-to-ambient  $(\theta_{JA})$  : See MIL-STD-1835 100°C/W 95°C/W 110°C/W +150°C -65°C to +150°C Lead temperature (soldering, 10 seconds) . . . . . . +300°C 1.4 Recommended operating conditions. Supply voltage (V<sub>CC</sub>) . . . . . . . . . . . . . . . . +4.5 V dc to +5.5 V dc Ambient operating temperature range ( $T_A$ ) . . . . . . -55°C to +125°C 2. APPLICABLE DOCUMENTS 2.1 Government specification, standards, bulletin, and handbook. Unless otherwise specified, the following specification, standards, bulletin, and handbook of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein. **SPECIFICATION** MILITARY MIL-I-38535 - Integrated Circuits, Manufacturing, General Specification for. **STANDARDS** MILITARY MIL-STD-883 - Test Methods and Procedures for Microelectronics. MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines. BULLETIN **MILITARY** MIL-BUL-103 - List of Standardized Military Drawings (SMD's). HANDBOOK MILITARY MIL-HDBK-780 - Standardized Military Drawings. (Copies of the specification, standards, bulletin, and handbook required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.) 1/ Must withstand the added  $P_D$  due to short circuit test; e.g.,  $I_{OS}$  $\frac{1}{2}$ / Case E derates at 10 mW/°C, case V derates at 10.53 mW/°C and case 2 derates at 9.09 mW/°C above T<sub>A</sub> = +70°C. **STANDARDIZED** SIZE 5962-94565 MILITARY DRAWING A DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444 REVISION LEVEL SHEET 3 DESC FORM 193A

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2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

### 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device class M shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. The individual item requirements for device classes Q and V shall be in accordance with MIL-I-38535, the device manufacturer's Quality Management (QM) plan, and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V and herein.
  - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein.
  - 3.2.2 Truth table(s). The truth table(s) shall be as specified on figure 1.
  - 3.2.3 Terminal connections. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. Marking for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein). In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103. Marking for device classes Q and V shall be in accordance with MIL-I-38535.
- 3.5.1 <u>Certification/compliance mark</u>. The compliance mark for device class M shall be a "C" as required in MIL-STD-883 (see 3.1 herein). The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-I-38535.
- 3.6 <u>Certificate of compliance</u>. For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.7.2 herein). For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.7.1 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device class M, the requirements of MIL-STD-883 (see 3.1 herein), or for device classes Q and V, the requirements of MIL-I-38535 and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device class M in MIL-STD-883 (see 3.1 herein) or for device classes Q and V in MIL-I-38535 shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change for device class M. For device class M, notification to DESC-EC of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.
- 3.9 <u>Verification and review for device class M</u>. For device class M, DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 77 (see MIL-I-38535, appendix A).

### 4. QUALITY ASSURANCE PROVISIONS

4.1 <u>Sampling and inspection</u>. For device class M, sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein). For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-I-38535 and the device manufacturer's QM plan.

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Test	Symbol	Conditions <u>1</u> /	Group	A	Device	<u>Limits</u>		Unit	
		$-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ +4.5 V dc $\leq \hat{V}_{\text{CC}} \leq +5.5$ V (unless otherwise specifie	dc subgro	ups	type	Min	Max		
RS-232 TRANSMIT	TERS								
Output voltage swing	VOLTOUT	TR1, TR2 each loaded with 3 K	2 to GND 1, 2,	3	ALL	±5.0		V	
Input logic low threshold voltage	VILTIN	V <sub>OUT</sub> = high	1, 2,	3	ALL		0.8	<u> </u>	
Input logic high threshold voltage	VIHTIN	V <sub>OUT</sub> = low	1, 2,	3	All	2.0		<u> </u>	
Logic pull-up/input	ILTIN	normal mode	1, 2,	3	ALL		40	$\mu$ A	
current	1	SHDN = 0 V, shutdown mode			02,04		±1		
Output leakage current	IOLTOUT	v <sub>CC</sub> = 5.5 v, v <sub>OUT</sub> = ±15 v, SH	DN = 0 V 1, 2,	3	02,04		±10	μΑ	
$v_{CC} = \overline{SHDN} = 0 \text{ V, } v_{OUT} = \pm 15$		v .		02,04		±10			
		v <sub>CC</sub> = 0 v, v <sub>OUT</sub> = ± 15 v			01,03 05		±10		
Output short circuit current	IOSTOUT	V <sub>CUT</sub> = 0 V	1, 2,	3	ALL	±7		mA	
Transition slew rate	tSLEW	C <sub>L</sub> = 50 pF to 2500 pF, R <sub>L</sub> = 3	kΩ to 9		01	1.5	30	V/µs	
		$7 \text{ k}\Omega$ , $V_{\text{CC}} = 5 \text{ V}$ , measured fro to $-3 \text{ V}$ or $-3 \text{ V}$ to $+3 \text{ V}$	m +3 V		02,03 04,05	6.0	30		
Data rate	f <sub>MAX</sub>	  normal mode	1, 2,	. 3	01		20	   kbits/se	
	,				02,03 04,05		116		
Transmitter output resistance	R <sub>TOUT</sub>	v <sub>cc</sub> = v+ = v- = 0 v, v <sub>out</sub> = ±	2 v   1, 2	, 3	All	300		Ω	
RS-232 RECEIVER	s								
RS-232 Input voltage range	VINRIN		1, 2	, 3	ALL		±25	V	
RS-232 logic low threshold voltage	VILRIN	All receiver inputs except de type 05 R2 <sub>IN</sub> , V <sub>CC</sub> = 5 V	evice   1, 2	, 3	ALL	0.8		V	
		Input R2 <sub>IN</sub> only, V <sub>CC</sub> = 5 V, see figure 1	2/		05	   <b>-</b> 3.0			
See footenotes at end	d of tabl								
MI		DRAWING	SIZE A				59	62-9456	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444				TOTON.	LEVEL	SHE	· FT		

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Test	Symbol	Conditions 1/		Group A	Device	Limits		Unit
		-55°C \le T_A \le +125°C +4.5 V dc \le V_{CC} \le +5.5 (unless otherwise speci	; V dc fied)	subgroups	type	Min	Max	 
RS-232 RECEIVER	S - conti	nued						
RS-232 logic high threshold voltage	VIH <sub>RIN</sub>	All receiver inputs except   type 05 R2 <sub>IN</sub> , V <sub>CC</sub> = 5 V	device	1, 2, 3	ALL		2.4	v
		  Input R2 <sub>IN</sub> only, V <sub>CC</sub> = 5 V,  see figure 1	<u>2</u> /		05		-0.1	 
RS-232 hysteresis input voltage	VHYSRIN	  Normal mode, all receiver i  except device type 05 R2 <sub>IN</sub> ,	nputs	1, 2, 3	ALL	0.2	1.0	V
		Input R2 <sub>IN</sub> only, V <sub>CC</sub> = 5 V		05	1.0	 		
RS-232 input resistance	R <sub>IN</sub>		1, 2, 3	All	3.0	7.0	kΩ	
TTL/CMOS output voltage low	VOLROUT	  I <sub>OUT</sub> = 3.2 mA	1, 2, 3	ALL		0.4	v	
TTL/CMOS output voltage high	VOHROUT	I <sub>OUT</sub> = 1.0 mA	1, 2, 3	ALL	3.5		V	
TTL/CMOS output short circuit	IOS <sub>ROUT</sub>	DS <sub>ROUT</sub> Sourcing V <sub>OUT</sub> = GND		1, 2, 3	ALL	-2		mA
current		  Sinking V <sub>OUT</sub> = V <sub>CC</sub>			10			
TTL/CMOS output leakage current	IOLROUT	SHDN = 0 V, 0 V \leq V_OUT \leq V_C	c	1, 2, 3	02		±10	μA
	   	EN = V <sub>CC</sub> , O V ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub>			04		±10	
EN input low threshold voltage	VILEN			1, 2, 3	04		0.8	٧
EN input high threshold voltage	VIHEN			1, 2, 3	04	2.0		V
Shutdown input leakage current	IILSHDN			1, 2, 3	02,04		±1	μΑ
Shutdown input low threshold voltage	VILSHDN			1, 2, 3	02,04		0.8	ν
Shutdown input high threshold voltage	VIHSHDN			1, 2, 3	02,04	2.0		٧
See footnotes at end	of table.							
STANDARDIZED MILITARY DRAWING		SIZE A				596	52-94565	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444				DEV	ISION	COVET	SHE	 7Т

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Test	Symbol	Conditions 1/	Group A	Device	Lim	its	Unit
		-55°C ≤ T <sub>A</sub> ≤ +125°C   +4.5 V dc ≤ V <sub>CC</sub> ≤ +5.5 V dc   (unless otherwise specified)	subgroups	type	Min	Max	
POWER SUPPLY							
Supply voltage	v <sub>cc</sub>		1, 2, 3	All	4.5	5.5	V
Supply current	Icc	  No load, normal mode	1, 2, 3	01		2	mA
				02,03, 04,05		10	
Shutdown supply current	ICCSHON	Shutdown mode, SHDN = 0 V	1	02,04		10	μА
			2, 3			100	
AC CHARACTERIST	1	T	0 40 44	T		10	
Transmitter propagation delay, TTL to RS-232	t <sub>PHLT</sub>	Normal mode, see figure 3	9, 10, 11	01  02,03,  04,05		3.5	μs
Receiver propagation	t <sub>PHLR</sub>	  Normal mode, see figure 3	9, 10, 11	01		3.0	μs
delay time, RS-232 to TTL	t <sub>PLHR</sub>			02,03,		1.0	
	t <sub>PHLS</sub>	Shutdown mode, SHDN = 0 V,   see figure 3	9, 10, 11	04		10	
Receiver to output enable time	tER	See figure 3	9, 10, 11	04		500	ns
Receiver to output	t <sub>DR</sub>	  See figure 3	9, 10, 11	04	 	500	ns

<sup>1/</sup> For device types 02, 03, 04, 05, all external capacitors = 0.1  $\mu$ F. For device type 01, external capacitors C1, C2, and C5 = 4.7  $\mu$ F, C3 and C4 = 10  $\mu$ F. For device type 05, R2<sub>OUT</sub> is low when the receiver R2<sub>IN</sub> is  $\geq$  0 V or is floating. 3/ For design purposes only, not tested.

Device type 05									
Receiver input	R1 output	R2 output							
≤ -3 V	High	High							
Open	High	Low							
≥ +3 V	Low	Low							

FIGURE 1. Truth table.

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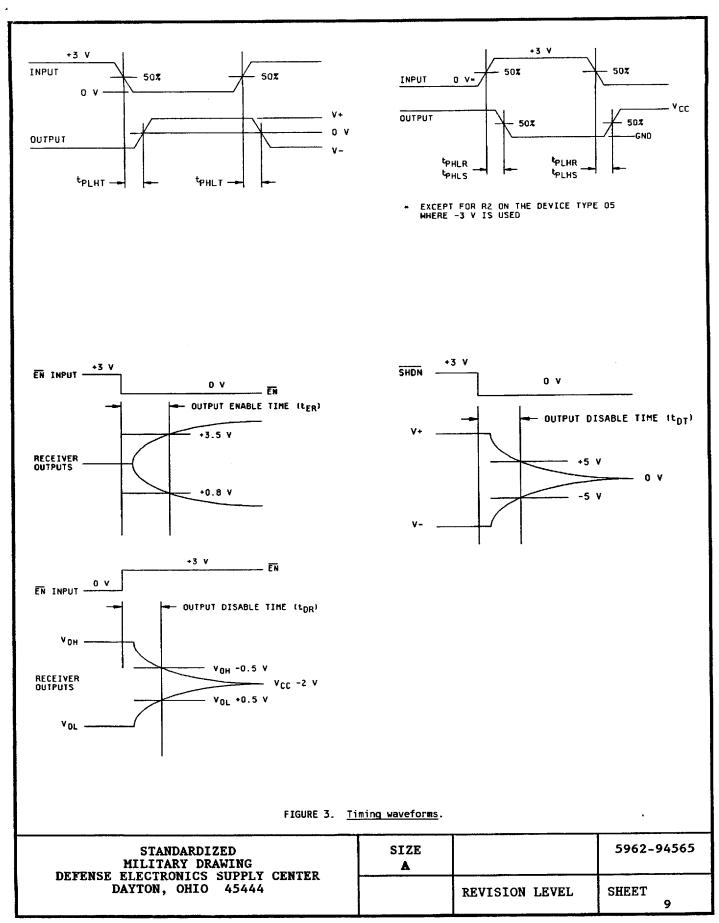
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Device type	01,03	3,05	02	!	04	
Case outline	E_	2	v	2	v	2
Terminal number			Terminal	symbol		
1	C1+	NC	NC	NC	EN	EN
2	V+	C1+	C1+	C1+	c1+	C1+
3	C1-	٧+	V+	V+	V+	V+
4	C2+	C1-	C1-	C1-	c1-	C1-
5	c2-	c2+	c2+	c2+	C2+	C2+
6	٧-	NC	c2-	NC	C2-	NC
7	T2 <sub>OUT</sub>	c2-	V-	c2-	V-	C2-
8	R2 <sub>IN</sub>	V-	T2 <sub>OUT</sub>	V-	T2 <sub>OUT</sub>	V-
9	R2 <sub>OUT</sub>	T2 <sub>OUT</sub>	R2 <sub>IN</sub>	T2 <sub>OUT</sub>	R2 <sub>IN</sub>	T2 <sub>OUT</sub>
10	T2 <sub>IN</sub>	R2 <sub>IN</sub>	R2 <sub>OUT</sub>	R2 <sub>IN</sub>	R2 <sub>OUT</sub>	R2 <sub>IN</sub>
11	T1 <sub>IN</sub>	NC .	T2 <sub>IN</sub>	NC	T2 <sub>IN</sub>	NC
12	R1 <sub>OUT</sub>	R2 <sub>OUT</sub>	T1 <sub>IN</sub>	R2 <sub>OUT</sub>	T1 <sub>IN</sub>	R2 <sub>OUT</sub>
13	R7 <sub>IN</sub>	T2 <sub>IN</sub>	R1 <sub>OUT</sub>	T2 <sub>IN</sub>	R1 <sub>OUT</sub>	T2 <sub>IN</sub>
14	T1 <sub>OUT</sub>	T1 <sub>IN</sub>	R1 <sub>IN</sub>	T1 <sub>IN</sub>	R1 <sub>IN</sub>	T1 <sub>IN</sub>
   15	GND	R1 <sub>OUT</sub>	T1 <sub>OUT</sub>	R1 <sub>OUT</sub>	T1 <sub>OUT</sub>	R1 <sub>OUT</sub>
16	V <sub>CC</sub>	NC NC	GND	R1 <sub>IN</sub>	GND	R1 <sub>IN</sub>
17	-	R1 IN	V <sub>CC</sub>	T <sup>1</sup> OUT	V <sub>CC</sub>	T1 <sub>OUT</sub>
18	-	T <sup>1</sup> OUT	SHDN	GND	SHDN	GND
19	!   -	GND	-	V <sub>cc</sub>	-	V <sub>CC</sub>
20	   -	V <sub>CC</sub>	   <b>-</b> 	SHDN	   - 	SHDN

FIGURE 2. <u>Terminal connections</u>.

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- 4.2 <u>Screening</u>. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. For device classes Q and V, screening shall be in accordance with MIL-I-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.
  - 4.2.1 Additional criteria for device class M.
    - a. Burn-in test, method 1015 of MIL-STD-883.
      - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
      - (2)  $T_A = +125$ °C, minimum.
    - b. Interim and final electrical test parameters shall be as specified in table II herein.
  - 4.2.2 Additional criteria for device classes Q and V.
    - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-I-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
    - b. Interim and final electrical test parameters shall be as specified in table II herein.
    - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in appendix B of MIL-1-38535.
- 4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-I-38535. Inspections to be performed shall be those specified in MIL-I-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Quality conformance inspection for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein) and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4). Technology conformance inspection for classes Q and V shall be in accordance with MIL-I-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-I-38535 permits alternate in-line control testing.
  - 4.4.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, 6, 7 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
- 4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.
  - 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
    - a. Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.
    - b.  $T_A = +125$ °C, minimum.
    - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups Subgroups (in accordance with (in accordance MIL-STD-883, MIL-1-38535, tab TM 5005, table 1)		with	
	Device class M	Device class Q	Device class V	
Interim electrical parameters (see 4.2)	1	1	1	
Final electrical parameters (see 4.2)	1/ 1, 2, 3, 9, 10, 11	1/ 1, 2, 3, 9, 10, 11	1/ 1, 2, 3, 9, 10, 11	
Group A test requirements (see 4.4)	1, 2, 3, 9, 10, 11	1, 2, 3, 9, 10, 11	1, 2, 3, 9, 10, 11	
Group C end-point electrical parameters (see 4.4)	1	1	1, 2, 3, 9, 10, 11	
Group D end-point electrical parameters (see 4.4)	1	1	1	
Group E end-point electrical parameters (see 4.4)				

<sup>1/</sup> PDA applies to subgroup 1.

- 4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB, in accordance with MIL-I-38535, and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.
- 4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.
- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes Q and V shall be M, D, R, and H and for device class M shall be M and D.
  - a. End-point electrical parameters shall be as specified in table II herein.
  - b. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-I-38535, appendix A, for the RHA level being tested. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-I-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T<sub>A</sub> = +25°C ±5°C, after exposure, to the subgroups specified in table II herein.
  - c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

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### 5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V.

### 6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
  - 6.1.2 <u>Substitutability</u>. Device class Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.3 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and which SMD's are applicable to that system. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-I-38535 and MIL-STD-1331.
- 6.6 One part one part number system. The one part one part number system described below has been developed to allow for transitions between identical generic devices covered by the three major microcircuit requirements documents (MIL-H-38534, MIL-I-38535, and 1.2.1 of MIL-STD-883) without the necessity for the generation of unique PIN's. The three military requirements documents represent different class levels, and previously when a device manufacturer upgraded military product from one class level to another, the benefits of the upgraded product were unavailable to the Original Equipment Manufacturer (OEM), that was contractually locked into the original unique PIN. By establishing a one part number system covering all three documents, the OEM can acquire to the highest class level available for a given generic device to meet system needs without modifying the original contract parts selection criteria.

Military documentation format	Example PIN under new system	Manufacturing source listing	Document listing
New MIL-H-38534 Standardized Military Drawings	5962-XXXXXZZ(H or K)YY	QML-38534	MIL-BUL-103
New MIL-I-38535 Standardized Military Drawings	5962-XXXXXZZ(Q or V)YY	QML-38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standardized Military Drawings	5962-XXXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

## 6.7 Sources of supply.

- 6.7.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DESC-EC and have agreed to this drawing.
- 6.7.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

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